



Product data sheet

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SOD-323



FEATURES

- Low Turn-on Voltage
- Fast Switching
- PN Junction Guard for Transient and ESD Protection
- Designed for Surface Mount Application
- Plastic Material –UL Recognition Flammability Classification 94V-O

MARKING: K73



| 0 | | | |
|--------------------------------------------------------|------------------|------------|------|
| Parameter | Symbol | Limit | Unit |
| Peak Repetitive Peak Reverse Voltage | V _{RRM} | | |
| Working Peak Reverse Voltage | V _{RWM} | 70 | V |
| DC Blocking Voltage | V _R | | |
| Forward Continuous Current | I _F | 70 | mA |
| Bcb!fYdYhhj YPeak Forward Surge Current 4 hl, " a g | I _{FSM} | 100 | mA |
| Power Dissipation | PD | 200 | mW |
| Thermal Resistance from Junction to Ambient | $R_{\theta JA}$ | 500 | °C/W |
| Operating Junction Temperature Range | TJ | -40 ~ +125 | °C |
| Storage Temperature Range | T _{STG} | -55 ~ +150 | °C |

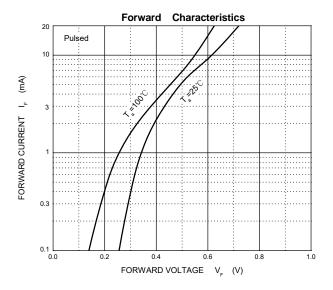
Maximum Ratings and Electrical Characteristics, Single Diode @Ta=25

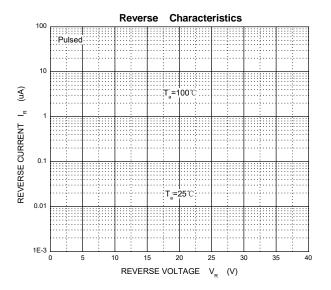
Electrical Ratings @Ta=25°C

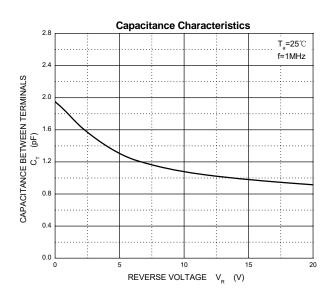
| Parameter | Symbol | Min | Тур | Max | Unit | Conditions |
|-------------------------------|-----------------|-----|-----|------|------|--------------------------------------------------------------------------------------|
| Forward valtage | V _{F1} | | | 0.41 | V | I _F =1mA |
| Forward voltage | V _{F2} | | | 1 | V | I _F =15mA |
| Reverse current | I _R | | | 100 | nA | V _R =50V |
| Capacitance between terminals | CT | | | 2 | pF | V _R =0V,f=1MHz |
| Reverse recovery time | t _{rr} | | | 5 | ns | I _F =I _R =10mA Irr=0.1XI _R ,R _L =100Ω |

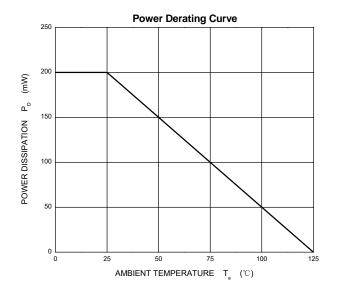






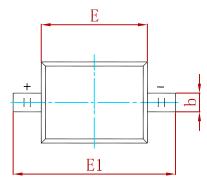


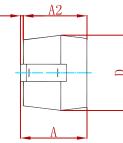




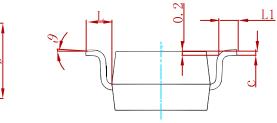


PACKAGE MECHANICAL DATA



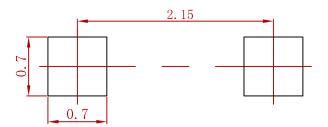


<u>A1</u>



| Cymhal | Dimensions | In Millimeters | Dimensions In Inches | | |
|--------|------------|----------------|----------------------|-------|--|
| Symbol | Min. | Max. | Min. | Max. | |
| A | | 1.000 | | 0.039 | |
| A1 | 0.000 | 0.100 | 0.000 | 0.004 | |
| A2 | 0.800 | 0.900 | 0.031 | 0.035 | |
| b | 0.250 | 0.350 | 0.010 | 0.014 | |
| с | 0.080 | 0.150 | 0.003 | 0.006 | |
| D | 1.200 | 1.400 | 0.047 | 0.055 | |
| E | 1.600 | 1.800 | 0.063 | 0.071 | |
| E1 | 2.550 | 2.750 | 0.100 | 0.108 | |
| L | 0.475 REF. | | 0.019 REF. | | |
| L1 | 0.250 | 0.400 | 0.010 | 0.016 | |
| θ | 0° | 8° | 0° | 8° | |

Suggested Pad Layout



Note:

1.Controlling dimension:in millimeters.

2.General tolerance:± 0.05mm.

3. The pad layout is for reference purposes only.

REEL SPECIFICATION

| P/N | PKG | QTY |
|---------|---------|------|
| BAS70WS | SOD-323 | 3000 |





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